

Nch 650V 9A Power MOSFET

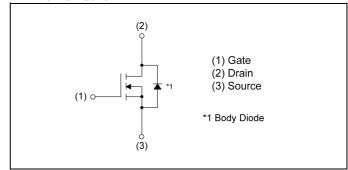
V_{DSS}	650V
R _{DS(on)} (Max.)	0.585Ω
I _D	±9A
P _D	48W

● Outline TO-220FM (1)(2)(3)

Features

- 1) Low on-resistance
- 2) Ultra fast switching speed
- 3) Parallel use is easy
- 4) Pb-free plating; RoHS compliant

•Inner circuit



Application

Switching

Packaging specifications

Packing	Bulk
Packing code	-
Marking	R6509KNX
Basic ordering unit (pcs)	500

ullet Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V _{DSS}	650	V
Continuous drain current (T _c = 25°C)		I _D *1	±9	Α
Pulsed drain current		I _{DP} *2	±27	Α
Coto Course vallesse	static	V	±20	V
Gate - Source voltage	AC(f>1Hz)	V _{GSS}	±30	V
Avalanche current, single pulse		I _{AS}	1.4	Α
Avalanche energy, single pulse		E _{AS} *3	158	mJ
Power dissipation (T _c = 25°C)	P _D	48	W	
Junction temperature	T _j	150	°C	
Operating junction and storage tempera	ature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Davamatav	Cymah al	Values			1.114
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *4	-	-	2.6	°C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	70	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

● Electrical characteristics (T_a = 25°C)

Parameter	Cumb al	Conditions	Values			Unit
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = 1mA$	650	-	-	V
		$V_{DS} = 650V, V_{GS} = 0V$				
Zero gate voltage drain current	I _{DSS}	T _j = 25°C	-	-	100	μΑ
aram carrent		T _j = 125°C	-	-	1000	
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	1	-	±100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 230 \mu A$	3	-	5	V
		V _{GS} = 10V, I _D = 2.8A				
Static drain - source on - state resistance	R _{DS(on)} *5	$T_j = 25^{\circ}C$	-	0.530	0.585	Ω
		T _j = 125°C	-	_	-	
Gate resistance	R_{G}	f = 1MHz, open drain	-	3.1	-	Ω

● Electrical characteristics (T_a = 25°C)

Davameter	Symbol	Conditions		Lloit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	540	-	
Output capacitance	C _{oss}	V _{DS} = 25V	-	550	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	25	-	
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 300V$, $V_{GS} = 10V$	-	20	-	
Rise time	t _r *5	I _D = 4.5A	-	20	-	
Turn - off delay time	t _{d(off)} *5	$R_L \simeq 66.7\Omega$	-	38	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	20	-	

● Gate charge characteristics (T_a = 25°C)

Davamatar	C: reals al	Conditions	Values			1.1-24
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit
Total gate charge	Q_g^{*5}	V _{DD} ≈ 300V	-	16.5	-	
Gate - Source charge	Q _{gs} *5	I _D = 9A	-	4.5	-	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = 10V	-	7.6	-	
Gate plateau voltage	V _(plateau)	V _{DD} ≈ 300V, I _D = 9.0A	-	6.9	-	V

^{*1} Limited only by maximum channel temperature allowed.

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L \doteqdot 100mH, V_{DD}=50V, R_G=25 Ω , STARTING T_j=25 $^{\circ}$ C

^{*4} T_C=25°C

^{*5} Pulsed

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Source current	I _S *1	T - 25°C	1	-	9	Α
Pulsed source current	I _{SP} *2	T _C = 25°C	1	-	27	Α
Source-Drain voltage	V _{SD} *5	$V_{GS} = 0V, I_{S} = 9.0A$	-	-	1.5	٧
Reverse recovery time	t _{rr} *5		-	360	-	ns
Reverse recovery charge	Q _{rr} *5	I _S = 9A di/dt = 100A/μs	-	3.6	-	μC
Peak reverse recovery current	l _m *5		-	20	-	Α

Fig.1 Power Dissipation Derating Curve

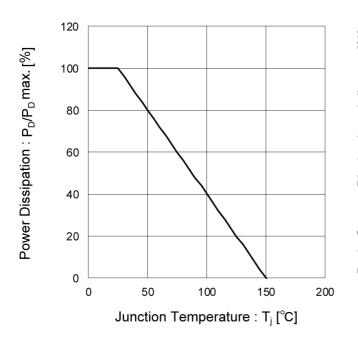


Fig.2 Drain Current Derating Curve

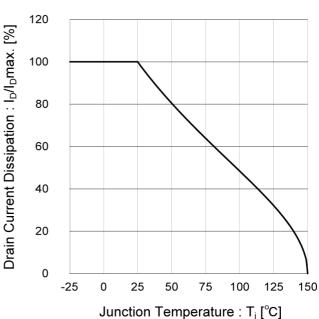


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

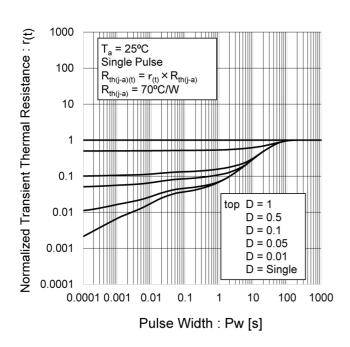
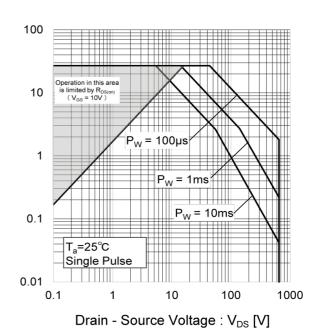


Fig.4 Maximum Safe Operating Area



Drain Current : I_D [A]

Fig.5 Avalanche Energy Derating
Curve vs. Junction Temperature

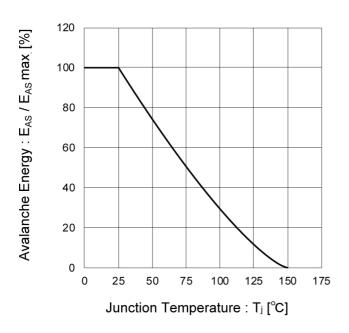


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

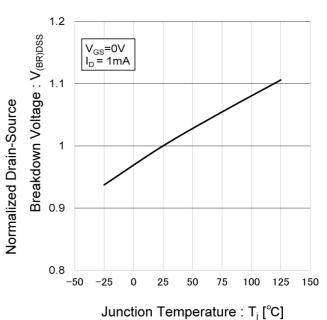


Fig.7 Typical Output Characteristics(I)

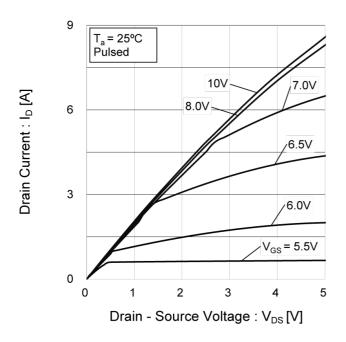
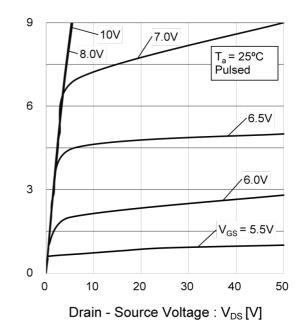


Fig.8 Typical Output Characteristics(II)



Drain Current : I_D [A]

Fig.9 Typical Transfer Characteristics

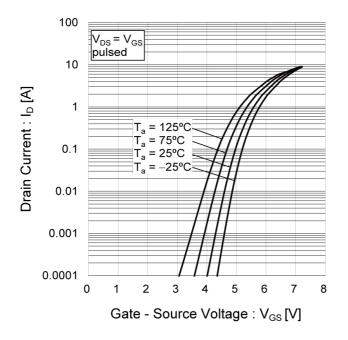


Fig.10 Normalized Gate Threshold .

Voltage vs Junction Temperature

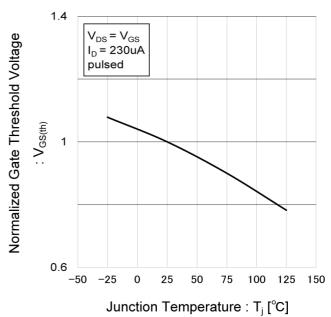


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

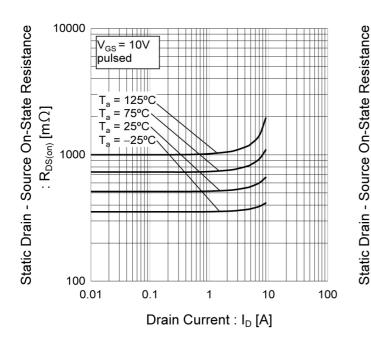


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

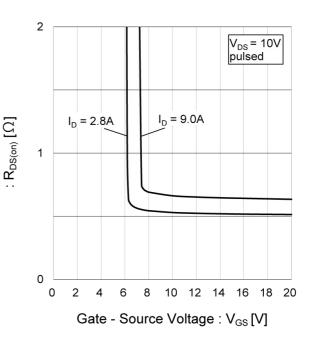


Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

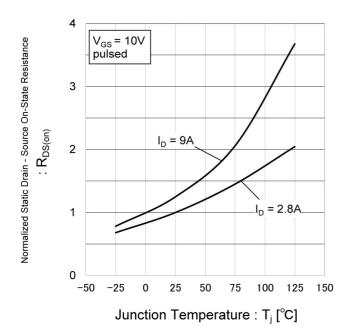


Fig.14 Typical Capacitance vs.
Drain - Source Voltage

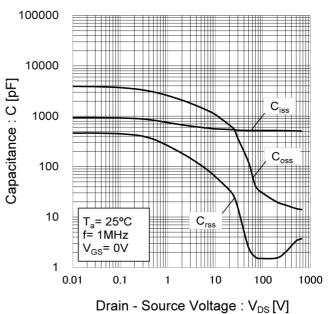


Fig.15 Switching Characteristics

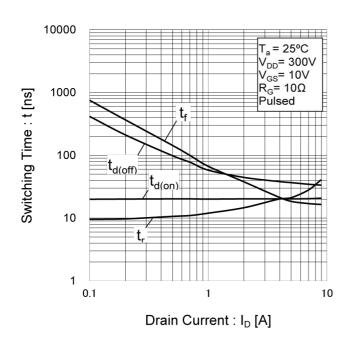
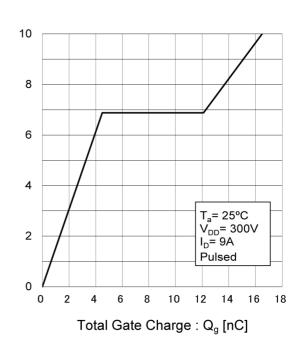
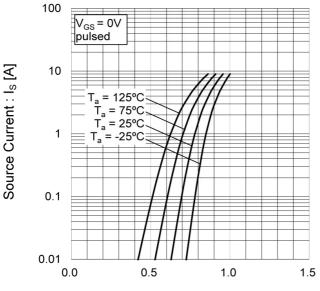


Fig.16 Typical Gate Charge



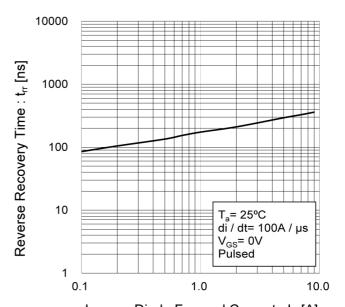
Gate - Source Voltage : V_{GS} [V]

Fig.17 Source Current vs. Source - Drain Voltage



Source - Drain Voltage : V_{SD} [V]

Fig.18 Reverse Recovery Time vs. Inverse Diode Forward Current



Inverse Diode Forward Current: I_S [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

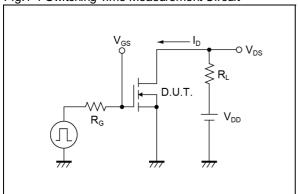


Fig.2-1 Gate Charge Measurement Circuit

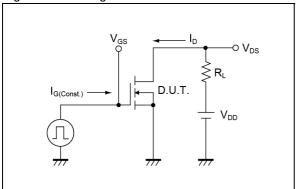


Fig.3-1 Avalanche Measurement Circuit

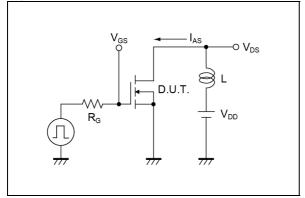


Fig.4-1 trr Measurement Circuit

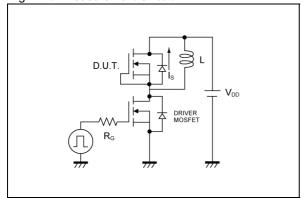


Fig.1-2 Switching Waveforms

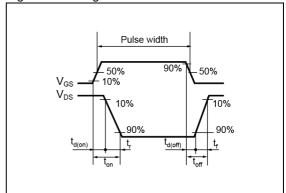


Fig.2-2 Gate Charge Waveform

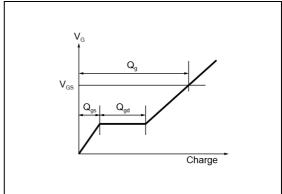


Fig.3-2 Avalanche Waveform

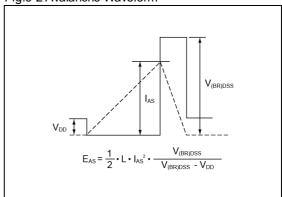
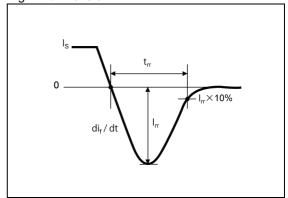
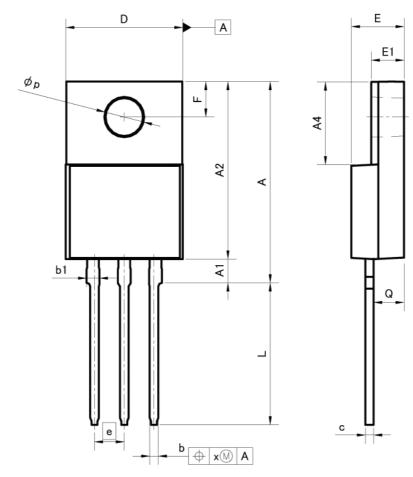


Fig.4-2 trr Waveform



Dimensions





DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	16.60	17.60	0.654	0.693
A1	1.80	2.20	0.071	0.087
A2	14.80	15.40	0.583	0.606
A4	6.80	7.20	0.268	0.283
b	0.70	0.90	0.028	0.035
b1	1.10	1.50	0.043	0.059
С	0.70	0.85	0.028	0.033
D	9.90	10.30	0.390	0.406
E	4.40	4.80	0.173	0.189
е	2.	54	0.100	
E1	2.70	3.00	0.106	0.118
F	2.80	3.20	0.110	0.126
L	11.50	12.50	0.453	0.492
р	3.00	3.40	0.118	0.134
Q	2.10	3.10	0.083	0.122
Х	W_*	0.38		0.015

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
CLASSⅢ	CI ACCIII	CLASS II b	CI VCCIII
CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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R6509KNX - Web Page

Part Number	R6509KNX
Package	TO-220FM
Unit Quantity	500
Minimum Package Quantity	100
Packing Type	Bulk
Constitution Materials List	inquiry
RoHS	Yes